

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
24 June 2004 (24.06.2004)

PCT

(10) International Publication Number
WO 2004/053787 A1

(51) International Patent Classification⁷: **G06K 19/077**

(21) International Application Number:
PCT/KR2003/000304

(22) International Filing Date: 13 February 2003 (13.02.2003)

(25) Filing Language: Korean

(26) Publication Language: English

(30) Priority Data:
10-2002-0077164 6 December 2002 (06.12.2002) KR
10-2003-0002366 14 January 2003 (14.01.2003) KR
10-2003-0002592 15 January 2003 (15.01.2003) KR

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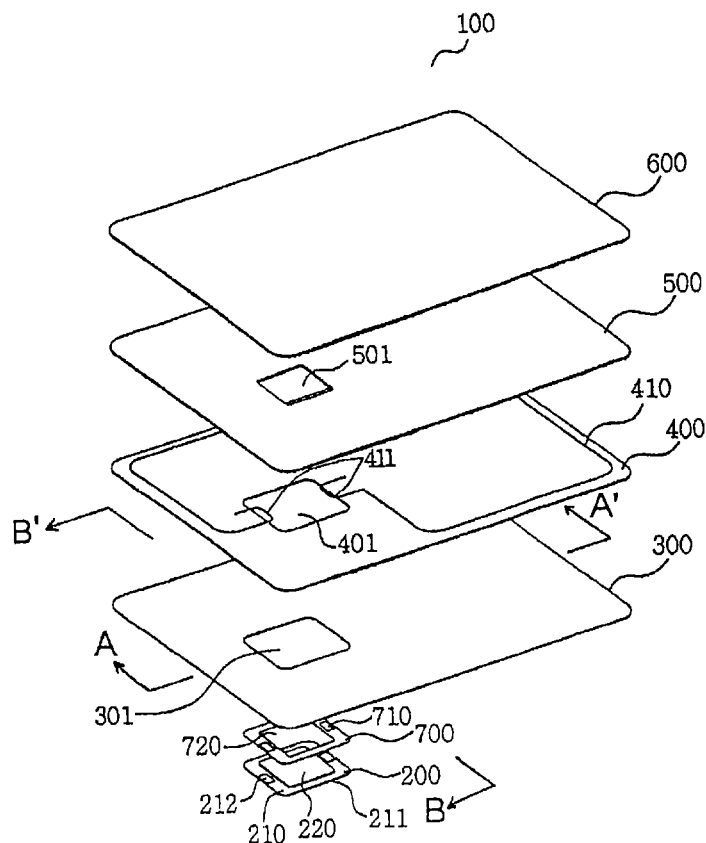
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(81) Designated States (national): AE, AG, AL, AM, AT, AU,
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,
CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,
GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK,
LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX,
MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SK,
SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN,
YU, ZA, ZM, ZW.

(84) Designated States (regional): ARIPO patent (GH, GM,
KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),

[Continued on next page]

(54) Title: METHOD FOR MANUFACTURING IC CARD BY LAMINATING A PLURALITY OF FOILS



(57) Abstract: The present invention provides a method for manufacturing IC card by laminating a plurality of foils. The method of the present invention includes steps of putting a COB, a contact electrode of the COB facing downward; laying at least 2 foils having a hole, wherein said COB is inserted in said respective holes of the foils; laying a foil not having a hole on the foils having a hole; and compressing all of the foils.



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Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE,
ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, SE, SI,
SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, ML, MR, NE, SN, TD, TG).

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

Published:

— with international search report